Lattice Semiconductor Corporation - LFSCM3GA80EP1-6FFN1704I Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

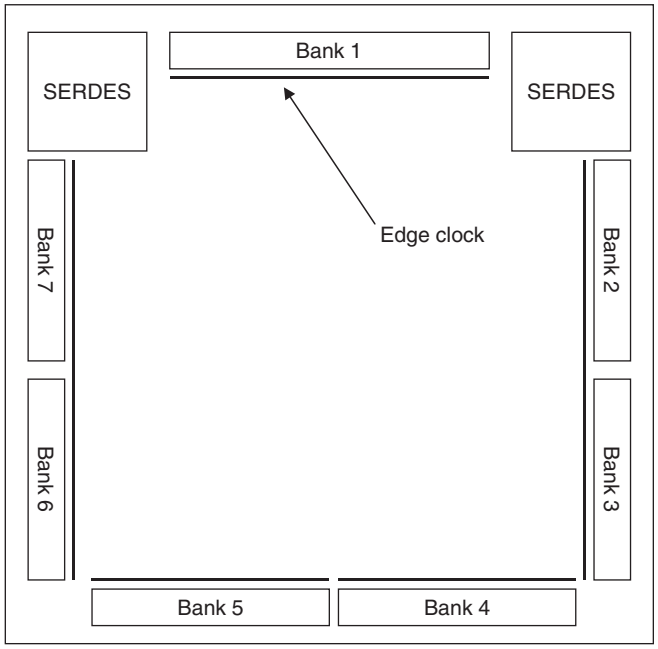
Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	20000
Number of Logic Elements/Cells	80000
Total RAM Bits	5816320
Number of I/O	904
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 105°C (TJ)
Package / Case	1704-BBGA, FCBGA
Supplier Device Package	1704-OFCBGA (42.5x42.5)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga80ep1-6ffn1704i

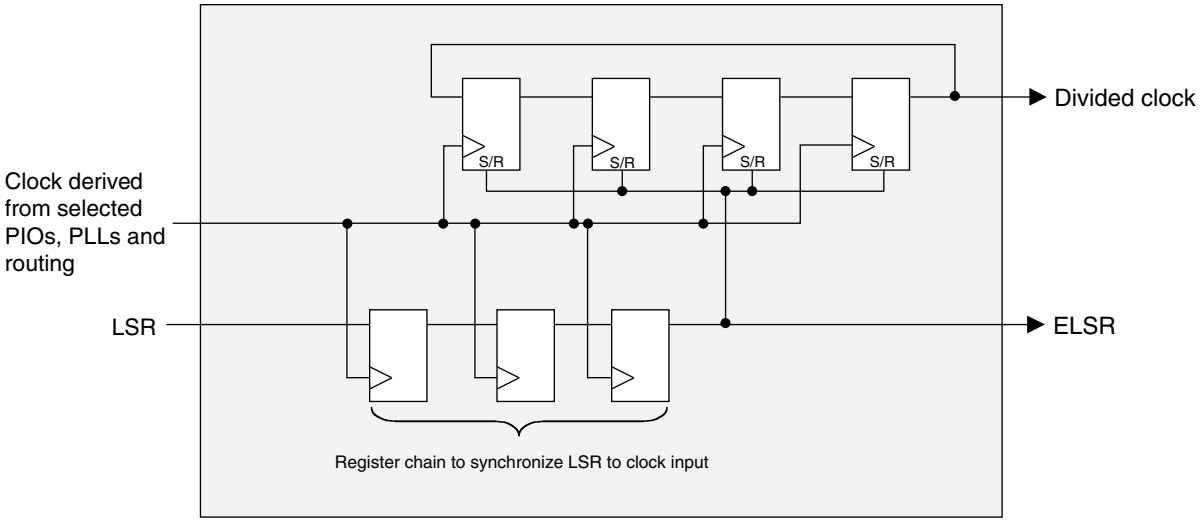
Figure 2-7. Edge Clock Resources



Precision Clock Divider

Each set of edge clocks has four high-speed dividers associated with it. These are intended for generating a slower speed system clock from the high-speed edge clock. The block operates in a DIV2 or DIV4 mode and maintains a known phase relationship between the divided down clock and high-speed clock based on the release of its reset signal. The clock dividers can be fed from selected PIOs, PLLs and routing. The clock divider outputs serve as primary clock sources. This circuit also generates an edge local set/reset (ELSR) signal which is fed to the PIOs via the edge clock network and is used for the rest of the I/O gearing logic.

Figure 2-8. Clock Divider Circuit



Dynamic Clock Select (DCS)

The DCS is a global clock buffer with smart multiplexer functions. It takes two independent input clock sources and outputs a clock signal without any glitches or runt pulses. This is achieved irrespective of where the select signal is

PURESPEED I/O Buffer Banks

LatticeSC devices have seven PURESPEED I/O buffer banks; each is capable of supporting multiple I/O standards. Each PURESPEED I/O bank has its own I/O supply voltage (V_{CCIO}), and two voltage references V_{REF1} and V_{REF2} resources allowing each bank to be completely independent from each other. Figure 2-26 shows the seven banks and their associated supplies. Table 2-7 lists the maximum number of I/Os per bank for the whole LatticeSC family.

In the LatticeSC devices, single-ended output buffers and ratioed input buffers (LVTTL, LVCMOS, PCI33 and PCIX33) are powered using V_{CCIO}. In addition to the bank V_{CCIO} supplies, the LatticeSC devices have a V_{CC} core logic power supply, and a V_{CCAUX} supply that power all differential and referenced buffers. VCCAUX also powers a predriver of single-ended output buffers to enhance buffer performance.

Each bank can support up to two separate VREF voltages, VREF1 and VREF2 that set the threshold for the referenced input buffers. In the LatticeSC devices any I/O pin in a bank can be configured to be a dedicated reference voltage supply pin. Each I/O is individually configurable based on the bank's supply and reference voltages.

Differential drivers have user selectable internal or external bias. External bias is brought in by the VREF1 pin in the bank. External bias for differential buffers is needed for applications that requires tighter than standard output common mode range.

Since a bank can have only one external bias circuit for differential drivers, LVDS and RSDS differential outputs can be mixed in a bank.

If a differential driver is configured in a bank, one pin in that bank becomes a DIFFR pin. This DIFFR pin must be connected to ground via an external 1K +/-1% ohm resistor. Note that differential drivers are not supported in banks 1, 4 and 5.

In addition, there are dedicated Terminating Supply (V_{TT}) pins to be used as terminating voltage for one of the two ways to perform parallel terminations. These V_{TT} pins are available in banks 2-7, these pins are not available in some packages. When VTT termination is not required, or used to provide the common mode termination voltage (VCMT), these pins can be left unconnected on the device. If the internal or external VCMT function for differential input termination is used, the VTT pins should be unconnected and allowed to float.

There are further restrictions on the use of V_{TT} pins, for additional details refer to technical information at the end of this data sheet.

this allows for easy integration with the rest of the system. These capabilities make the LatticeSC ideal for many multiple power supply and hot-swap applications. The maximum current during hot socketing is 4mA. See Hot Socketing Specifications in Chapter 3 of this data sheet.

Power-Up Requirements

To prevent high power supply and input pin currents, each VCC, VCC12, VCCAUX, VCCIO and VCCJ power supplies must have a monotonic ramp up time of 75 ms or less to reach its minimum operating voltage. Apart from VCC and VCC12, which have an additional requirement, and VCCIO and VCCAUX, which also have an additional requirement, the VCC, VCC12, VCCAUX, VCCIO and VCCJ power supplies can ramp up in any order, with no restriction on the time between them. However, the ramp time for each must be 75 ms or less. Configuration of the device will not proceed until the last power supply has reached its minimum operating voltage.

Additional Requirement for VCC and VCC12:
VCC12 must always be higher than VCC. This condition must be maintained at ALL times, including during power-up and power-down. Note that for 1.2V only operation, it is advisable to source both of these supplies from the same power supply.

Additional Requirement for VCCIO and VCCAUX:
If any VCCIOs are 1.2/1.5/1.8V, then VCCAUX MUST be applied before them. If any VCCIO is 1.2/1.5/1.8V and is powered up before VCCAUX, then when VCCAUX is powered up, it may drag VCCIO up with it as it crosses through the VCCIO value. (Note: If the VCCIO supply is capable of sinking current, as well as the more usual sourcing capability, this behavior is eliminated. However, the amount of current that the supply needs to sink is unknown and is likely to be in the hundreds of milliamps range).

Power-Down Requirements

To prevent high power supply and input pin currents, power must be removed monotonically from either VCC or VCCAUX (and must reach the power-down trip point of 0.5V for VCC, 0.95V for VCCAUX) before power is removed monotonically from VCC12, any of the VCCIOs, or VCCJ. Note that VCC12 can be removed at the same time as VCC, but it cannot be removed earlier. In many applications, VCC and VCC12 will be sourced from the same power supply and so will be removed together. For systems where disturbance of the user pins is a don't care condition, the power supplies can be removed in any order as long as they power down monotonically within 200ms of each other.

Additionally, if any banks have VCCIO=3.3V nominal (potentially banks 1, 4, 5) then VCCIO for those banks must not be lower than VCCAUX during power-down. The normal variation in ramp-up times of power supplies and voltage regulators is not a concern here.

Note: The SERDES power supplies are NOT included in these requirements and have no specific sequencing requirements. However, when using the SERDES with VDDIB or VDDOB that is greater than 1.2V (1.5V nominal for example), the SERDES should not be left in a steady state condition with the 1.5V power applied and the 1.2V power not applied. Both the 1.2V and 1.5V power should be applied to the SERDES at nominally the same time. The normal variation in the ramp-up times of power supplies and voltage regulators is not a concern here.

SERDES Power Supply Sequencing Requirements

When using the SERDES with 1.5V VDDIB or VDDOB supplies, the SERDES should not be left in a steady state condition with the 1.5V power applied and the 1.2V power not applied. Both the 1.2V and the 1.5V power should be applied to the SERDES at nominally the same time. The normal variation in ramp-up times of power supples and voltage regulators is not a concern.

Additional Requirement for SERDES Power Supply
All VCC12 pins need to be connected on all devices independent of functionality used on the device. This analog supply is used by both the RX and TX portions of the SERDES and is used to control the core SERDES logic regardless of the SERDES being used in the design. VDDIB and VDDOB are used as supplies for the terminations on the CML input and output buffers. If a particular channel is not used, these can be UNCONNECTED (floating).

Typical Building Block Function Performance

Over Recommended Commercial Operating Conditions at VCC = 1.2V +/- 5%

Pin to Pin Performance (LVCMOS25 12 mA Drive)

Function	-7*	Units
Basic Functions		
32-bit Decoder	6.65	ns
Combinatorial (Pin to LUT to Pin)	5.58	ns
Embedded Memory Functions (Single Port RAM)		
Pin to EBR Input Register Setup (Global Clock)	1.66	ns
EBR Output Clock to Pin (Global Clock)	8.54	ns
Distributed (PFU) RAM (Single Port RAM)		
Pin to PFU RAM Register Setup (Global Clock)	1.32	ns
PFU RAM Clock to Pin (Global Clock)	6.83	ns

*Typical performance per function

Register-to-Register Performance

Function	-7*	Units
Basic Functions		
32-Bit Decoder	539	MHz
64-Bit Decoder	517	MHz
16:1 MUX	1003	MHz
32:1 MUX	798	MHz
16-Bit Adder	672	MHz
64-Bit Adder	353	MHz
16-Bit Counter	719	MHz
64-Bit Counter	369	MHz
32x8 SP RAM (PFU, Output Registered)	768	MHz
128x8 SP RAM (PFU, Output Registered)	545	MHz
Embedded Memory Functions		
Single Port RAM (512x36 Bits)	372	MHz
True Dual Port RAM 1024x18 Bits (No EBR Out Reg)	326	MHz
True dual port RAM 1024x18 Bits (EBR Reg)	372	MHz
FIFO port (A: x36 bits, B: x9 Bits, No EBR Out Reg)	353	MHz
FIFO port (A: x36 bits, B: x9 Bits, EBR Reg)	375	MHz
True DP RAM Width Cascading (1024x72)	372	MHz
DSP Functions		
9x9 1-stage Multiplier	209	MHz
18x18 1-Stage Multiplier	155	MHz
9x9 3-Stage Pipelined Multiplier	373	MHz
18x18 4-Stage Pipelined Multiplier	314	MHz
9x9 Constant Multiplier	372	MHz

*Typical performance per function

LatticeSC/M sysCONFIG Port Timing

Over Recommended Operating Conditions

Parameter	Description	Min.	Max.	Units
General Configuration Timing				
t_{SMODE}	M[3:0] Setup Time to INITN High	0	—	ns
t_{HMODE}	M[3:0] Hold Time from INITN High	600	—	ns
t_{RW}	RESETN Pulse Width Low to Start Reconfiguration (1.2 V)	50 (or 100 at 0.95V)	—	ns
t_{PGW}	PROGRAMN Pulse Width Low to Start Reconfiguration (1.2 V)	50 (or 100 at 0.95V)	—	ns
$f_{ESB\_CLK\_FRQ}$	System Bus ESB_CLK Frequency (No Wait States)	—	133	MHz
sysCONFIG Master Parallel Configuration Mode				
t_{SMB}	D[7:0] Setup Time to RCLK High	6	—	ns
t_{HMB}	D[7:0] Hold Time to RCLK High	0	—	ns
t_{CLMB}	RCLK Low Time (Non-compressed Bitstreams)	0.5	0.5	CCLK periods
	RCLK Low Time (Compressed Bitstreams)	0.5	7.5	CCLK periods
t_{CHMB}	RCLK High Time	0.5	0.5	CCLK periods
sysCONFIG SPI Port				
t_{CFGX}	INITN High to CSCK Low	—	80	ns
t_{CSSPI}	INITN High to CSSPIN Low	0	2	µs
t_{SCK}	CSCK Low before CSSPIN Low	0	—	ns
t_{SOCDO}	CSCK Low to Output Valid	—	15	ns
t_{CSPID}	CSSPIN Low to CSCK high Setup Time	—	15	ns
f_{MAXSPI}	Max CCLK Frequency - SPI Flash Fast Read Opcode (0x0B) (SPIFASTN=0)	—	50	MHz
t_{SUSPI}	SOSPI/D0 Data Setup Time Before CSCK	7	—	ns
t_{HSPI}	SOSPI/D0 Data Hold Time After CSCK	2	—	ns
	Master Clock Frequency	Selected value - 30%	Selected value + 30%	MHz
	Duty Cycle	40	60	%
sysCONFIG Master Serial Configuration Mode				
t_{SMS}	DIN Setup Time	4.4	—	ns
t_{HMS}	DIN Hold Time	0	—	ns
f_{CMS}	CCLK Frequency (No Divider)	90	190	MHz
f_{C_DIV}	CCLK Frequency (Div 128)	0.70	1.48	MHz
t_{D}	CCLK to DOUT Delay	—	7.5	ns
sysCONFIG Master Parallel Configuration Mode				
t_{AVMP}	RCLK to Address Valid	—	10	ns
t_{SMP}	D[7:0] Setup Time to RCLK High	6	—	ns
t_{HMP}	D[7:0] Hold Time to RCLK High	0	—	ns
t_{CLMP}	RCLK Low Time (Non-compressed Bitstream)	7.5	7.5	CCLK periods
	RCLK Low Time (Compressed Bitstream)	0.5	63.5	
t_{CHMP}	RCLK High Time	0.5	0.5	CCLK periods
t_{DMP}	CCLK to DOUT	—	7.5	ns

Switching Test Conditions

Figure 3-15 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Table 3-4.

Figure 3-15. Output Test Load, LVTTL and LVCMOS Standards

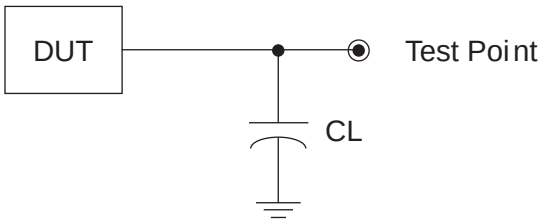


Table 3-4. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	C_L	Timing Ref.	V_T
LVTTL and other LVCMOS settings (L -> H, H -> L)	30pF	LVCMOS 3.3 = 1.5V	—
		LVCMOS 2.5 = $V_{CCIO}/2$	—
		LVCMOS 1.8 = $V_{CCIO}/2$	—
		LVCMOS 1.5 = $V_{CCIO}/2$	—
		LVCMOS 1.2 = $V_{CCIO}/2$	—
LVCMOS 2.5 I/O (Z -> H)	30pF	$V_{CCIO}/2$	V_{OL}
LVCMOS 2.5 I/O (Z -> L)		$V_{CCIO}/2$	V_{OH}
LVCMOS 2.5 I/O (H -> Z)		V_{OH} - 0.15	V_{OL}
LVCMOS 2.5 I/O (L -> Z)		V_{OL} + 0.15	V_{OH}

Note: Output test conditions for all other interfaces are determined by the respective standards.

Signal Descriptions (Cont.)

Signal Name	I/O	Description
RESETN		Reset. (Also sent to general routing). During configuration it resets the configuration state machine. After configuration this pin can perform the global set/reset (GSR) functions or can be used as a general input pin.
CFGIRQN	O	MPI Interrupt request active low signal is controlled by system bus interrupt controller and may be sourced from any bus error or MPI configuration error. It can be connected to one of MPC860 IRQ pins.
TSALLN	I	Tristates all I/O.
Configuration Pads (User I/O if not used. Used during sysCONFIG.)		
HDC/SI	O	High During Configuration is output high until configuration is complete. It is used as a control output, indicating that configuration is not complete. For SPI modes, this pin is used to download the read command and initial read address into the Flash memory device on the falling edge of SCK. This pin will be connected to SI of the memory. If the SPI mode is used, the 8-bit instruction code 0x03 will be downloaded followed by a 24-bit starting address of 0x000000 or a non-zero stat address for partial reconfiguration. If the SPIX mode has been selected, the 8-bit instruction captured on D[7:0] at power-up will be shifted in and followed by a 32-bit starting address of 0x000000.
LDCN/SCS	O	Low During Configuration is output low until configuration is complete. It is used as a control output, indicating that configuration is not complete. For SPI modes, this is an active low chip select for Flash memories. It will go active after INITN goes high but before SCK begins. During power up LDCN will be low. Once INITN goes high, LDCN will go high for 100ns-200ns after which time it will go back low and configuration can begin. During the 100ns-200ns period, the read instruction will be latched for SPIX mode.
DOUT	O	Serial data output that can drive the D0/DIN of daisy-chained slave devices. The data-stream from this output will propagate preamble bits of the bitstream to daisy-chained devices. Data out on DOUT changes on the rising edge of CCLK.
QOUT/CEON	O	During daisy-chaining configuration, QOUT is the serial data output that can drive the D0/DIN of daisy-chained slave devices that do not propagate preamble bits. Data out on QOUT changes on the rising edge of CCLK. During parallel-chaining configuration, active low CEON enables the cascaded slave device to receive bitstream data.
RDN	I	Used in the asynchronous peripheral configuration mode. A low on RDN changes D[7:3] into status outputs. WRN and RDN should not be used simultaneously. If they are, the write strobe overrides.
WRN	I	When the FPGA is selected, a low on the write strobe, WRN, loads the data on D[7:0] inputs into an internal data buffer.
CS0N CS1	I	Used in the asynchronous peripheral, slave parallel and MPI modes. The FPGA is selected when CS0N is low and CS1 is high. During configuration, a pull-up is enabled on both except with MPI DMA access control.
A[21:0]	I/O	In master parallel mode, A[21:0] is an output and will address the configuration EPROMs up to 4 MB space. For MPI configuration mode, A[17:0] will be the MPI address MPI_ADDR[31:14], A[19:18] will be the transfer size and A[21:20] will be the burst mode and burst in process.

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
G1	NC	-		PL20B	7	
M4	NC	-		NC	-	
J3	NC	-		NC	-	
P5	NC	-		NC	-	
W5	NC	-		PL48C	6	
T6	NC	-		PL35C	6	
U3	NC	-		PL36A	6	
V3	NC	-		PL36B	6	
T5	NC	-		PL39A	6	
T4	NC	-		PL39B	6	
V5	NC	-		PL43C	6	
U6	NC	-		PL42C	6	
U4	NC	-		PL40A	6	
U5	NC	-		PL40B	6	
V4	NC	-		PL43D	6	
Y2	NC	-		PL47A	6	
AA2	NC	-		PL47B	6	
W3	NC	-		PL47D	6	
Y3	NC	-		PL47C	6	
AB3	NC	-		NC	-	
AC4	NC	-		PL53A	6	
AD4	NC	-		PL53B	6	
AE3	NC	-		PL56A	6	
AF3	NC	-		PL56B	6	
AF7	NC	-		PB7A	5	
AF6	NC	-		PB7B	5	
AH4	NC	-		PB8A	5	
AG5	NC	-		PB8B	5	
AF8	NC	-		PB9A	5	
AG8	NC	-		PB9B	5	
AG7	NC	-		NC	-	
AG10	NC	-		NC	-	
AF12	NC	-		NC	-	
AH7	NC	-		PB15A	5	
AE13	NC	-		PB15D	5	
AG13	NC	-		PB23C	5	
AH8	NC	-		PB15B	5	
AJ5	NC	-		PB17A	5	
AJ6	NC	-		PB17B	5	
AF15	NC	-		PB21D	5	
AJ7	NC	-		PB19A	5	
AJ8	NC	-		PB19B	5	
AE12	NC	-		PB15C	5	
AF16	NC	-		PB38D	4	
AF19	NC	-		PB49D	4	

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
N17	GND	-		GND	-	
N18	GND	-		GND	-	
N19	GND	-		GND	-	
N20	GND	-		GND	-	
P11	GND	-		GND	-	
P12	GND	-		GND	-	
P13	GND	-		GND	-	
P14	GND	-		GND	-	
P15	GND	-		GND	-	
P16	GND	-		GND	-	
P17	GND	-		GND	-	
P18	GND	-		GND	-	
P19	GND	-		GND	-	
P20	GND	-		GND	-	
R10	GND	-		GND	-	
R11	GND	-		GND	-	
R12	GND	-		GND	-	
R13	GND	-		GND	-	
R14	GND	-		GND	-	
R15	GND	-		GND	-	
R16	GND	-		GND	-	
R17	GND	-		GND	-	
R18	GND	-		GND	-	
R19	GND	-		GND	-	
R20	GND	-		GND	-	
R21	GND	-		GND	-	
T10	GND	-		GND	-	
T11	GND	-		GND	-	
T12	GND	-		GND	-	
T13	GND	-		GND	-	
T14	GND	-		GND	-	
T15	GND	-		GND	-	
T16	GND	-		GND	-	
T17	GND	-		GND	-	
T18	GND	-		GND	-	
T19	GND	-		GND	-	
T20	GND	-		GND	-	
T21	GND	-		GND	-	
U11	GND	-		GND	-	
U12	GND	-		GND	-	
U13	GND	-		GND	-	
U14	GND	-		GND	-	
U15	GND	-		GND	-	
U16	GND	-		GND	-	
U17	GND	-		GND	-	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
AJ34	PL98A	6	
AK34	PL98B	6	
AB27	PL98C	6	
AC27	PL98D	6	
AF33	PL99A	6	
AG33	PL99B	6	
AC29	PL99C	6	
AD29	PL99D	6	
AE31	PL103A	6	
AF31	PL103B	6	
AF30	PL103C	6	
AF29	PL103D	6	
AH33	PL104A	6	
AJ33	PL104B	6	
AC28	PL104C	6	
AD28	PL104D	6	
AH32	PL107A	6	
AJ32	PL107B	6	
AD27	PL107C	6	
AE27	PL107D	6	VREF2_6
AG34	PL109A	6	
AH34	PL109B	6	
AC26	PL109C	6	
AB26	PL109D	6	
AK33	PL112A	6	
AL33	PL112B	6	
AG30	PL112C	6	
AH30	PL112D	6	
AL34	PL115A	6	
AM34	PL115B	6	
AJ30	PL115C	6	LLC_DLLT_IN_E/LLC_DLLT_FB_F
AK30	PL115D	6	LLC_DLLC_IN_E/LLC_DLLC_FB_F
AJ31	PL116A	6	
AH31	PL116B	6	
AD26	PL116C	6	
AD25	PL116D	6	
AL32	PL117A	6	LLC_DLLT_IN_F/LLC_DLLT_FB_E
AL31	PL117B	6	LLC_DLLC_IN_F/LLC_DLLC_FB_E
AG29	PL117C	6	LLC_PLLT_IN_B/LLC_PLLT_FB_A
AG28	PL117D	6	LLC_PLLC_IN_B/LLC_PLLC_FB_A
AF28	XRES	-	
AF27	TEMP	6	
AM33	PB3A	5	LLC_PLLT_IN_A/LLC_PLLT_FB_B

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
L21	PT55D	1	A16/MPI_ADDR30
L20	PT55C	1	D13/MPI_DATA13
D20	PT55B	1	A15/MPI_ADDR29
E20	PT55A	1	A17/MPI_ADDR31
L19	PT54D	1	A19/MPI_TSIZ1
K19	PT54C	1	A20/MPI_BDIP
D21	PT54B	1	A18/MPI_TSIZ0
E21	PT54A	1	MPI_TEA
M20	PT51D	1	D14/MPI_DATA14
M19	PT51C	1	DP1/MPI_PAR1
F21	PT51B	1	A21/MPI_BURST
G21	PT51A	1	D15/MPI_DATA15
H24	B_REFCLKP_L	-	
J24	B_REFCLKN_L	-	
L22	VCC12	-	
E26	B_VDDIB3_L	-	
G22	VCC12	-	
E22	B_HDINP3_L	-	PCS 361 CH 3 IN P
F22	B_HDINN3_L	-	PCS 361 CH 3 IN N
A21	B_HDOUTP3_L	-	PCS 361 CH 3 OUT P
L24	VCC12	-	
B21	B_HDOUTN3_L	-	PCS 361 CH 3 OUT N
D22	B_VDDOB3_L	-	
B22	B_HDOUTN2_L	-	PCS 361 CH 2 OUT N
D23	B_VDDOB2_L	-	
A22	B_HDOUTP2_L	-	PCS 361 CH 2 OUT P
K24	VCC12	-	
F23	B_HDINN2_L	-	PCS 361 CH 2 IN N
E23	B_HDINP2_L	-	PCS 361 CH 2 IN P
D26	B_VDDIB2_L	-	
G23	VCC12	-	
D27	B_VDDIB1_L	-	
G24	VCC12	-	
E24	B_HDINP1_L	-	PCS 361 CH 1 IN P
F24	B_HDINN1_L	-	PCS 361 CH 1 IN N
A23	B_HDOUTP1_L	-	PCS 361 CH 1 OUT P
L25	VCC12	-	
B23	B_HDOUTN1_L	-	PCS 361 CH 1 OUT N
D24	B_VDDOB1_L	-	
B24	B_HDOUTN0_L	-	PCS 361 CH 0 OUT N
D25	B_VDDOB0_L	-	
A24	B_HDOUTP0_L	-	PCS 361 CH 0 OUT P
K25	VCC12	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AF40	PL76A	6		PL90A	6	
AG40	PL76B	6		PL90B	6	
AG36	PL76C	6		PL90C	6	
AH36	PL76D	6	DIFFR_6	PL90D	6	DIFFR_6
AF39	PL77A	6		PL91A	6	
AG39	PL77B	6		PL91B	6	
AF29	PL77C	6		PL91C	6	
AG29	PL77D	6		PL91D	6	
AH42	PL78A	6		PL92A	6	
AG42	PL78B	6		PL92B	6	
AG35	PL78C	6		PL92C	6	
AH35	PL78D	6		PL92D	6	
AG41	PL80A	6		PL94A	6	
AH41	PL80B	6		PL94B	6	
AG34	PL80C	6		PL94C	6	
AH34	PL80D	6		PL94D	6	
AJ42	PL81A	6		PL96A	6	
AK42	PL81B	6		PL96B	6	
AG33	PL81C	6		PL96C	6	
AH33	PL81D	6		PL96D	6	
AJ41	PL82A	6		PL98A	6	
AK41	PL82B	6		PL98B	6	
AJ37	PL82C	6		PL98C	6	
AK37	PL82D	6		PL98D	6	
AJ40	PL84A	6		PL99A	6	
AK40	PL84B	6		PL99B	6	
AJ34	PL84C	6		PL99C	6	
AK34	PL84D	6		PL99D	6	
AJ38	PL85A	6		PL103A	6	
AK38	PL85B	6		PL103B	6	
AH32	PL85C	6		PL103C	6	
AJ32	PL85D	6		PL103D	6	
AL42	PL86A	6		PL104A	6	
AM42	PL86B	6		PL104B	6	
AK36	PL86C	6		PL104C	6	
AL36	PL86D	6		PL104D	6	
AL38	PL89A	6		PL107A	6	
AM38	PL89B	6		PL107B	6	
AJ33	PL89C	6		PL107C	6	
AK33	PL89D	6	VREF2_6	PL107D	6	VREF2_6
AN42	PL90A	6		PL109A	6	
AP42	PL90B	6		PL109B	6	
AH31	PL90C	6		PL109C	6	
AJ31	PL90D	6		PL109D	6	
AN41	PL91A	6		PL112A	6	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AE1	PR74A	3		PR88A	3	
AF12	PR73D	3		PR87D	3	
AE12	PR73C	3		PR87C	3	
AF2	PR73B	3		PR87B	3	
AE2	PR73A	3		PR87A	3	
AF11	PR72D	3		PR86D	3	
AE11	PR72C	3		PR86C	3	
AF5	PR72B	3		PR86B	3	
AE5	PR72A	3		PR86A	3	
AF10	PR69D	3		PR83D	3	
AE10	PR69C	3		PR83C	3	
AD1	PR69B	3		PR83B	3	
AC1	PR69A	3		PR83A	3	
AF9	PR68D	3		PR82D	3	
AE9	PR68C	3		PR82C	3	
AD2	PR68B	3		PR82B	3	
AC2	PR68A	3		PR82A	3	
AF6	PR67D	3		PR81D	3	
AE6	PR67C	3		PR81C	3	
AD3	PR67B	3		PR81B	3	
AC3	PR67A	3		PR81A	3	
AE8	PR65D	3		PR79D	3	
AD8	PR65C	3		PR79C	3	
AD4	PR65B	3		PR79B	3	
AC4	PR65A	3		PR79A	3	
AE7	PR64D	3		PR78D	3	
AD7	PR64C	3		PR78C	3	
AD5	PR64B	3		PR78B	3	
AC5	PR64A	3		PR78A	3	
AD6	PR63D	3		PR77D	3	
AC6	PR63C	3		PR77C	3	
AB1	PR63B	3		PR77B	3	
AA1	PR63A	3		PR77A	3	
AD9	PR61D	3		PR75D	3	
AC9	PR61C	3		PR75C	3	
AB2	PR61B	3		PR75B	3	
AA2	PR61A	3		PR75A	3	
AD14	PR60D	3		PR74D	3	
AC14	PR60C	3		PR74C	3	
AB5	PR60B	3		PR74B	3	
AA5	PR60A	3		PR74A	3	
AD10	PR59D	3		PR73D	3	
AC10	PR59C	3		PR73C	3	
Y1	PR59B	3		PR73B	3	
W1	PR59A	3		PR73A	3	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
J1	PR25B	2		PR38B	2	
K1	PR25A	2		PR38A	2	
V12	PR24D	2		PR34D	2	
U12	PR24C	2		PR34C	2	
K2	PR24B	2		PR34B	2	
J2	PR24A	2		PR34A	2	
R10	PR22D	2		PR30D	2	
T10	PR22C	2		PR30C	2	
L5	PR22B	2		PR30B	2	
K5	PR22A	2		PR30A	2	
P9	PR21D	2		PR26D	2	
N9	PR21C	2		PR26C	2	
L6	PR21B	2		PR26B	2	
K6	PR21A	2		PR26A	2	
M8	PR20D	2		PR19D	2	
M9	PR20C	2		PR19C	2	
H1	PR20B	2		PR19B	2	
G1	PR20A	2		PR19A	2	
U14	PR18D	2	VREF2_2	PR18D	2	VREF2_2
T14	PR18C	2		PR18C	2	
H2	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C
G2	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C
P10	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A
N10	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A
H3	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D
G3	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D
R11	PR16D	2		PR15D	2	
P11	PR16C	2		PR15C	2	
J5	PR16B	2	URC_PLLC_IN_A/URC_PLLC_FB_B	PR15B	2	URC_PLLC_IN_A/URC_PLLC_FB_B
J6	PR16A	2	URC_PLLT_IN_A/URC_PLLT_FB_B	PR15A	2	URC_PLLT_IN_A/URC_PLLT_FB_B
P18	VCCJ	-		VCCJ	-	
P19	TDO	-	TDO	TDO	-	TDO
R21	TMS	-		TMS	-	
P20	TCK	-		TCK	-	
P12	TDI	-		TDI	-	
P17	PROGRAMN	1		PROGRAMN	1	
P21	MPIIRQN	1	CFGIRQN/MPI_IRQ_N	MPIIRQN	1	CFGIRQN/MPI_IRQ_N
P13	CCLK	1		CCLK	1	
H10	RESP_URC	-		RESP_URC	-	
N13	VCC12	-		VCC12	-	
H9	A_REFCLKN_R	-		A_REFCLKN_R	-	
G9	A_REFCLKP_R	-		A_REFCLKP_R	-	
F2	VCC12	-		VCC12	-	
H4	A_VDDIB0_R	-		A_VDDIB0_R	-	
C1	A_HDINP0_R	-	PCS 3E0 CH 0 IN P	A_HDINP0_R	-	PCS 3E0 CH 0 IN P

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
D1	A_HDINN0_R	-	PCS 3E0 CH 0 IN N	A_HDINN0_R	-	PCS 3E0 CH 0 IN N
F1	VCC12	-		VCC12	-	
A3	A_HDOUTP0_R	-	PCS 3E0 CH 0 OUT P	A_HDOUTP0_R	-	PCS 3E0 CH 0 OUT P
E1	A_VDDOB0_R	-		A_VDDOB0_R	-	
B3	A_HDOUTN0_R	-	PCS 3E0 CH 0 OUT N	A_HDOUTN0_R	-	PCS 3E0 CH 0 OUT N
C2	A_VDDOB1_R	-		A_VDDOB1_R	-	
A4	A_HDOUTN1_R	-	PCS 3E0 CH 1 OUT N	A_HDOUTN1_R	-	PCS 3E0 CH 1 OUT N
B2	VCC12	-		VCC12	-	
B4	A_HDOUTP1_R	-	PCS 3E0 CH 1 OUT P	A_HDOUTP1_R	-	PCS 3E0 CH 1 OUT P
E3	A_HDINN1_R	-	PCS 3E0 CH 1 IN N	A_HDINN1_R	-	PCS 3E0 CH 1 IN N
D3	A_HDINP1_R	-	PCS 3E0 CH 1 IN P	A_HDINP1_R	-	PCS 3E0 CH 1 IN P
M10	VCC12	-		VCC12	-	
E2	A_VDDIB1_R	-		A_VDDIB1_R	-	
J11	VCC12	-		VCC12	-	
M11	A_VDDIB2_R	-		A_VDDIB2_R	-	
D4	A_HDINP2_R	-	PCS 3E0 CH 2 IN P	A_HDINP2_R	-	PCS 3E0 CH 2 IN P
E4	A_HDINN2_R	-	PCS 3E0 CH 2 IN N	A_HDINN2_R	-	PCS 3E0 CH 2 IN N
K9	VCC12	-		VCC12	-	
A5	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P
D2	A_VDDOB2_R	-		A_VDDOB2_R	-	
B5	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N
L10	A_VDDOB3_R	-		A_VDDOB3_R	-	
B6	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N
G6	VCC12	-		VCC12	-	
A6	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P
E5	A_HDINN3_R	-	PCS 3E0 CH 3 IN N	A_HDINN3_R	-	PCS 3E0 CH 3 IN N
D5	A_HDINP3_R	-	PCS 3E0 CH 3 IN P	A_HDINP3_R	-	PCS 3E0 CH 3 IN P
K12	VCC12	-		VCC12	-	
L13	A_VDDIB3_R	-		A_VDDIB3_R	-	
N14	VCC12	-		VCC12	-	
F9	B_VDDIB0_R	-		B_VDDIB0_R	-	
D6	B_HDINP0_R	-	PCS 3E1 CH 0 IN P	B_HDINP0_R	-	PCS 3E1 CH 0 IN P
E6	B_HDINN0_R	-	PCS 3E1 CH 0 IN N	B_HDINN0_R	-	PCS 3E1 CH 0 IN N
J8	VCC12	-		VCC12	-	
B7	B_HDOUTP0_R	-	PCS 3E1 CH 0 OUT P	B_HDOUTP0_R	-	PCS 3E1 CH 0 OUT P
G4	B_VDDOB0_R	-		B_VDDOB0_R	-	
A7	B_HDOUTN0_R	-	PCS 3E1 CH 0 OUT N	B_HDOUTN0_R	-	PCS 3E1 CH 0 OUT N
K8	B_VDDOB1_R	-		B_VDDOB1_R	-	
A8	B_HDOUTN1_R	-	PCS 3E1 CH 1 OUT N	B_HDOUTN1_R	-	PCS 3E1 CH 1 OUT N
L9	VCC12	-		VCC12	-	
B8	B_HDOUTP1_R	-	PCS 3E1 CH 1 OUT P	B_HDOUTP1_R	-	PCS 3E1 CH 1 OUT P
E7	B_HDINN1_R	-	PCS 3E1 CH 1 IN N	B_HDINN1_R	-	PCS 3E1 CH 1 IN N
D7	B_HDINP1_R	-	PCS 3E1 CH 1 IN P	B_HDINP1_R	-	PCS 3E1 CH 1 IN P
F10	VCC12	-		VCC12	-	
K13	B_VDDIB1_R	-		B_VDDIB1_R	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
D32	C_HDINP1_L	-	PCS 362 CH 1 IN P	C_HDINP1_L	-	PCS 362 CH 1 IN P
E32	C_HDINN1_L	-	PCS 362 CH 1 IN N	C_HDINN1_L	-	PCS 362 CH 1 IN N
B31	C_HDOUTP1_L	-	PCS 362 CH 1 OUT P	C_HDOUTP1_L	-	PCS 362 CH 1 OUT P
K32	VCC12	-		VCC12	-	
A31	C_HDOUTN1_L	-	PCS 362 CH 1 OUT N	C_HDOUTN1_L	-	PCS 362 CH 1 OUT N
L32	C_VDDOB1_L	-		C_VDDOB1_L	-	
A32	C_HDOUTN0_L	-	PCS 362 CH 0 OUT N	C_HDOUTN0_L	-	PCS 362 CH 0 OUT N
M31	C_VDDOB0_L	-		C_VDDOB0_L	-	
B32	C_HDOUTP0_L	-	PCS 362 CH 0 OUT P	C_HDOUTP0_L	-	PCS 362 CH 0 OUT P
H37	VCC12	-		VCC12	-	
E33	C_HDINN0_L	-	PCS 362 CH 0 IN N	C_HDINN0_L	-	PCS 362 CH 0 IN N
D33	C_HDINP0_L	-	PCS 362 CH 0 IN P	C_HDINP0_L	-	PCS 362 CH 0 IN P
G31	C_VDDIB0_L	-		C_VDDIB0_L	-	
J29	VCC12	-		VCC12	-	
L29	B_REFCLKP_L	-		B_REFCLKP_L	-	
M29	B_REFCLKN_L	-		B_REFCLKN_L	-	
J31	VCC12	-		VCC12	-	
H31	B_VDDIB3_L	-		B_VDDIB3_L	-	
J30	VCC12	-		VCC12	-	
D34	B_HDINP3_L	-	PCS 361 CH 3 IN P	B_HDINP3_L	-	PCS 361 CH 3 IN P
E34	B_HDINN3_L	-	PCS 361 CH 3 IN N	B_HDINN3_L	-	PCS 361 CH 3 IN N
B33	B_HDOUTP3_L	-	PCS 361 CH 3 OUT P	B_HDOUTP3_L	-	PCS 361 CH 3 OUT P
H38	VCC12	-		VCC12	-	
A33	B_HDOUTN3_L	-	PCS 361 CH 3 OUT N	B_HDOUTN3_L	-	PCS 361 CH 3 OUT N
C38	B_VDDOB3_L	-		B_VDDOB3_L	-	
A34	B_HDOUTN2_L	-	PCS 361 CH 2 OUT N	B_HDOUTN2_L	-	PCS 361 CH 2 OUT N
L31	B_VDDOB2_L	-		B_VDDOB2_L	-	
B34	B_HDOUTP2_L	-	PCS 361 CH 2 OUT P	B_HDOUTP2_L	-	PCS 361 CH 2 OUT P
G38	VCC12	-		VCC12	-	
E35	B_HDINN2_L	-	PCS 361 CH 2 IN N	B_HDINN2_L	-	PCS 361 CH 2 IN N
D35	B_HDINP2_L	-	PCS 361 CH 2 IN P	B_HDINP2_L	-	PCS 361 CH 2 IN P
H32	B_VDDIB2_L	-		B_VDDIB2_L	-	
K29	VCC12	-		VCC12	-	
K30	B_VDDIB1_L	-		B_VDDIB1_L	-	
F33	VCC12	-		VCC12	-	
D36	B_HDINP1_L	-	PCS 361 CH 1 IN P	B_HDINP1_L	-	PCS 361 CH 1 IN P
E36	B_HDINN1_L	-	PCS 361 CH 1 IN N	B_HDINN1_L	-	PCS 361 CH 1 IN N
B35	B_HDOUTP1_L	-	PCS 361 CH 1 OUT P	B_HDOUTP1_L	-	PCS 361 CH 1 OUT P
L34	VCC12	-		VCC12	-	
A35	B_HDOUTN1_L	-	PCS 361 CH 1 OUT N	B_HDOUTN1_L	-	PCS 361 CH 1 OUT N
K35	B_VDDOB1_L	-		B_VDDOB1_L	-	
A36	B_HDOUTN0_L	-	PCS 361 CH 0 OUT N	B_HDOUTN0_L	-	PCS 361 CH 0 OUT N
G39	B_VDDOB0_L	-		B_VDDOB0_L	-	
B36	B_HDOUTP0_L	-	PCS 361 CH 0 OUT P	B_HDOUTP0_L	-	PCS 361 CH 0 OUT P
J35	VCC12	-		VCC12	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AC24	GND	-		GND	-	
AC26	GND	-		GND	-	
AC35	GND	-		GND	-	
AC8	GND	-		GND	-	
AD12	GND	-		GND	-	
AD16	GND	-		GND	-	
AD18	GND	-		GND	-	
AD20	GND	-		GND	-	
AD23	GND	-		GND	-	
AD25	GND	-		GND	-	
AD27	GND	-		GND	-	
AD31	GND	-		GND	-	
AE17	GND	-		GND	-	
AE19	GND	-		GND	-	
AE24	GND	-		GND	-	
AE26	GND	-		GND	-	
AE3	GND	-		GND	-	
AE39	GND	-		GND	-	
AF18	GND	-		GND	-	
AF20	GND	-		GND	-	
AF23	GND	-		GND	-	
AF25	GND	-		GND	-	
AF36	GND	-		GND	-	
AF7	GND	-		GND	-	
AG11	GND	-		GND	-	
AG16	GND	-		GND	-	
AG19	GND	-		GND	-	
AG24	GND	-		GND	-	
AG27	GND	-		GND	-	
AG32	GND	-		GND	-	
AH15	GND	-		GND	-	
AH28	GND	-		GND	-	
AH4	GND	-		GND	-	
AH40	GND	-		GND	-	
AJ35	GND	-		GND	-	
AJ8	GND	-		GND	-	
AK12	GND	-		GND	-	
AK31	GND	-		GND	-	
AL13	GND	-		GND	-	
AL19	GND	-		GND	-	
AL24	GND	-		GND	-	
AL3	GND	-		GND	-	
AL30	GND	-		GND	-	
AL39	GND	-		GND	-	
AM16	GND	-		GND	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AM27	GND	-		GND	-	
AM36	GND	-		GND	-	
AM7	GND	-		GND	-	
AP4	GND	-		GND	-	
AP40	GND	-		GND	-	
AR14	GND	-		GND	-	
AR20	GND	-		GND	-	
AR23	GND	-		GND	-	
AR29	GND	-		GND	-	
AR35	GND	-		GND	-	
AR8	GND	-		GND	-	
AT11	GND	-		GND	-	
AT17	GND	-		GND	-	
AT26	GND	-		GND	-	
AT32	GND	-		GND	-	
AU3	GND	-		GND	-	
AU39	GND	-		GND	-	
AW12	GND	-		GND	-	
AW18	GND	-		GND	-	
AW22	GND	-		GND	-	
AW28	GND	-		GND	-	
AW34	GND	-		GND	-	
AW6	GND	-		GND	-	
AY15	GND	-		GND	-	
AY21	GND	-		GND	-	
AY25	GND	-		GND	-	
AY31	GND	-		GND	-	
AY37	GND	-		GND	-	
AY9	GND	-		GND	-	
B1	GND	-		GND	-	
B42	GND	-		GND	-	
BA1	GND	-		GND	-	
BA42	GND	-		GND	-	
BB2	GND	-		GND	-	
BB41	GND	-		GND	-	
C10	GND	-		GND	-	
C12	GND	-		GND	-	
C13	GND	-		GND	-	
C16	GND	-		GND	-	
C18	GND	-		GND	-	
C19	GND	-		GND	-	
C22	GND	-		GND	-	
C24	GND	-		GND	-	
C27	GND	-		GND	-	
C28	GND	-		GND	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
V21	VCC	-		VCC	-	
V22	VCC	-		VCC	-	
V23	VCC	-		VCC	-	
V25	VCC	-		VCC	-	
V27	VCC	-		VCC	-	
W17	VCC	-		VCC	-	
W19	VCC	-		VCC	-	
W21	VCC	-		VCC	-	
W22	VCC	-		VCC	-	
W24	VCC	-		VCC	-	
W26	VCC	-		VCC	-	
Y16	VCC	-		VCC	-	
Y18	VCC	-		VCC	-	
Y20	VCC	-		VCC	-	
Y23	VCC	-		VCC	-	
Y25	VCC	-		VCC	-	
Y27	VCC	-		VCC	-	
AG22	VCC12	-		VCC12	-	
AG26	VCC12	-		VCC12	-	
T17	VCC12	-		VCC12	-	
T21	VCC12	-		VCC12	-	
T22	VCC12	-		VCC12	-	
T26	VCC12	-		VCC12	-	
U16	VCC12	-		VCC12	-	
U27	VCC12	-		VCC12	-	
AC15	VCCAUX	-		VCCAUX	-	
AC28	VCCAUX	-		VCCAUX	-	
AD15	VCCAUX	-		VCCAUX	-	
AD28	VCCAUX	-		VCCAUX	-	
AE15	VCCAUX	-		VCCAUX	-	
AE28	VCCAUX	-		VCCAUX	-	
AF15	VCCAUX	-		VCCAUX	-	
AF28	VCCAUX	-		VCCAUX	-	
AG15	VCCAUX	-		VCCAUX	-	
AG28	VCCAUX	-		VCCAUX	-	
AH14	VCCAUX	-		VCCAUX	-	
AH16	VCCAUX	-		VCCAUX	-	
AH17	VCCAUX	-		VCCAUX	-	
AH18	VCCAUX	-		VCCAUX	-	
AH19	VCCAUX	-		VCCAUX	-	
AH20	VCCAUX	-		VCCAUX	-	
AH23	VCCAUX	-		VCCAUX	-	
AH24	VCCAUX	-		VCCAUX	-	
AH25	VCCAUX	-		VCCAUX	-	
AH26	VCCAUX	-		VCCAUX	-	

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the Thermal Management document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following located on the Lattice website at www.latticesemi.com.

- Thermal Management document
- Technical Note TN1101 - Power Estimation and Management for LatticeSC Devices
- Power Calculator tool included with Lattice's ispLEVER design tool, or as a standalone download from www.latticesemi.com/software